Total No. of Questions: 10 ] [ Total No. of Printed Pages: 3

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## EC-505

B. E. (Fifth Semester) EXAMINATION, Dec., 2011 (Electronics & Communication Engg. Branch)

CMOS VLSI DESIGN

(EC - 505)

Time : Three Hours Maximum Marks : 100 Minimum Pass Marks : 35

Note: Attempt any *one* question from each Unit. All Units are compulsory to attempt. All questions carry equal marks.

## Unit-I

- 1. (a) Explain the CMOS Inverter D. C. characteristic. How CMOS Inverter can be used as amplifier?
  - (b) Determine the type and the amount of Channel Ion Implantations which are necessary to achieve a threshold voltage of  $VT_0 = -2 V$  for P-Channel mosfet with the following parameters:
    - (i) Substrate doping density  $N_A = 10^{15}/\text{cm}^3$
    - (ii) Polysilicon gate doping density  $N_D = 10^{20}/cm^3$
    - (iii)  $T_{OX} = 650 \text{ Å}$
    - (iv)  $N_{OX} = 4 \times 10^{10} / \text{cm}^2$

Also calculate threshold voltage  $V_{T_0}$  for  $V_{SB}$  = 0. P. T. O

	[2]	EO
	Or	EC-505
(2	Write short notes on the following:  ii) Stick diagrams  iii) Channel length modulation  iii) Pass transistor	12
(b) E	iv) Tunneling	
(-) L	xplain briefly the MOS capacitance model.	8
	Unit-II	
3. (a) Extended teachers	xplain the following terms in reference of chnology:	VLSI
(i)	Wafer formation	20
(ii)	a continography	
(iii	) Oxidation	
(iv)	) Isolation	
(v)	Well and Channel formation	
	Or	
4. (a) What deve	at are VLSI interconnects? How interconnects eloped during IC fabrication? at are design rules? Explain MOSIS Design r	are 10
	Unit — III	10
5. (a) Expla		
paras (b) Expla	itic delay in CMOS circuit.	of 10
chip c	design: design:	
(i)	Capacitance	10
	Process variation	
(111)	Temperature	
	Reliability	
	· · · · · · · · · · · · · · · · · · ·	

## [ 3 ]

## Or

6.	(a)	What is power dissipation in CMOS? Explain static power dissipation and its cause. Explain different
		methods to reduce it.
	(b)	Explain the following terms: 8
		(i) Transmission sizing
		(ii) Interconnect scaling
	,	Unit-IV
7.	(a)	What are CMOS Op-Amp. and RF circuits? Explain
, •	(u)	them briefly.
	(b)	What are differential pains ? Explain them in brief
	(-)	with mathematical expression?
		Or
8.	(n)	What are current mirrors? Derive expression for it.
Ο,	(a)	10.
	(b)	10
	(b)	Explain the following.
		<ul><li>(i) MOS Small Signal Model</li><li>(ii) CMOS designed Analog to Digital Converter</li></ul>
8		Unit – V
9.	_	lain the following terms: 20
	(i)	Cell Hierarchies
	. ,	Cell Shapes
		Ratioed circuit
	(IV)	Cascode Voltage Switch logic
		Or
10	. Wh	at is BICMOS logic? Derive the expression for
		ching delay in BICMOS logic circuit? Explain different lications of BICMOS.
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